



Product Change Notification

Change Notification #: 118275-00
Change Title: Select Intel® Server Chassis H2000P Family,
PCN 118275-00, Transport Media,
Packaging Kit Change
Date of Publication: May 27, 2021

Key Characteristics of the Change:

Transport Media

Forecasted Key Milestones:

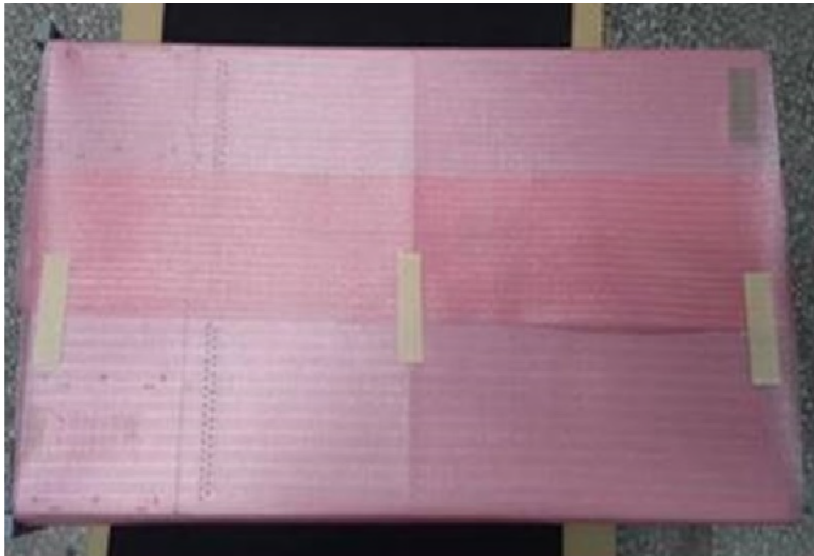
Date Customer Must be Ready to Receive Post-Conversion Material:	June 11, 2021
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

The Intel® Server Chassis listed in the products affected table below will have the following change.

- Intel is implementing an improvement by adding an extra EPE film sheet for covering Chassis in packing kit as illustrated below:



Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from the change but encourages customers to understand the change and determine the impact on their applications.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change TA	Post Change TA
Intel® Server Chassis H2224XXLR3, Single	H2224XXLR3	948907	J57870-008	J57870-009

PCN Revision History:

Date of Revision:

May 27, 2021

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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